

1 Electrical ratings

Table 1. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|---|-------------|------------------|
| V_{GS} | Gate-source voltage | ± 30 | V |
| I_D | Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$ | 6 | A |
| I_D | Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$ | 4 | A |
| $I_{DM}^{(1)}$ | Drain current pulsed | 24 | A |
| P_{TOT} | Total dissipation at $T_C = 25\text{ }^\circ\text{C}$ | 110 | W |
| $dv/dt^{(2)}$ | Peak diode recovery voltage slope | 4.5 | V/ns |
| $dv/dt^{(3)}$ | MOSFET dv/dt ruggedness | 50 | |
| T_j | Operating junction temperature range | - 55 to 150 | $^\circ\text{C}$ |
| T_{stg} | Storage temperature range | | |

1. Pulse width limited by safe operating area.
2. $I_{SD} \leq 6\text{ A}$, $di/dt \leq 100\text{ A}/\mu\text{s}$; $V_{DS\text{ peak}} \leq V_{(BR)DSS}$
3. $V_{DS} \leq 640\text{ V}$

Table 2. Thermal data

| Symbol | Parameter | Value | Unit |
|---------------------|----------------------------------|-------|---------------------------|
| $R_{thj-case}$ | Thermal resistance junction-case | 1.14 | $^\circ\text{C}/\text{W}$ |
| $R_{thj-pcb}^{(1)}$ | Thermal resistance junction-pcb | 50 | $^\circ\text{C}/\text{W}$ |

1. When mounted on 1inch² FR-4 board, 2 oz Cu

Table 3. Avalanche characteristics

| Symbol | Parameter | Value | Unit |
|----------|---|-------|------|
| I_{AR} | Avalanche current, repetitive or not repetitive (pulse width limited by $T_{jmax.}$) | 2 | A |
| E_{AS} | Single pulse avalanche energy (starting $T_j = 25\text{ }^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$) | 114 | mJ |

2 Electrical characteristics

$T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise specified

Table 4. On/off-state

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|-----------------------------------|--|------|------|----------|---------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage | $V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$ | 800 | | | V |
| I_{DSS} | Zero gate voltage drain current | $V_{GS} = 0\text{ V}$, $V_{DS} = 800\text{ V}$ | | | 1 | μA |
| | | $V_{GS} = 0\text{ V}$, $V_{DS} = 800\text{ V}$ | | | 50 | μA |
| | | $T_C = 125\text{ }^{\circ}\text{C}$ ⁽¹⁾ | | | | |
| I_{GSS} | Gate body leakage current | $V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20\text{ V}$ | | | ± 10 | μA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}$, $I_D = 100\text{ }\mu\text{A}$ | 3 | 4 | 5 | V |
| $R_{DS(on)}$ | Static drain-source on-resistance | $V_{GS} = 10\text{ V}$, $I_D = 3\text{ A}$ | | 0.8 | 0.95 | Ω |

1. Defined by design, not subject to production test.

Table 5. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-------------------|---------------------------------------|---|------|------|------|----------|
| C_{iss} | Input capacitance | $V_{DS} = 100\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$ | - | 450 | - | pF |
| C_{oss} | Output capacitance | | - | 50 | - | pF |
| C_{rss} | Reverse transfer capacitance | | - | 1 | - | pF |
| $C_{o(tr)}^{(1)}$ | Equivalent capacitance time related | $V_{DS} = 0\text{ to }640\text{ V}$, $V_{GS} = 0\text{ V}$ | - | 57 | - | pF |
| $C_{o(er)}^{(2)}$ | Equivalent capacitance energy related | | | 24 | - | pF |
| R_g | Intrinsic gate resistance | $f = 1\text{ MHz}$, $I_D = 0\text{ A}$ | - | 6 | - | Ω |
| Q_g | Total gate charge | $V_{DD} = 640\text{ V}$, $I_D = 6\text{ A}$ | - | 16.5 | - | nC |
| Q_{gs} | Gate-source charge | $V_{GS} = 0\text{ to }10\text{ V}$ | - | 3.2 | - | nC |
| Q_{gd} | Gate-drain charge | (see Figure 15. Test circuit for gate charge behavior) | - | 11 | - | nC |

1. $C_{o(tr)}$ is a constant capacitance value that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

2. $C_{o(er)}$ is a constant capacitance value that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

Table 6. Switching times

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|--------------|---------------------|---|------|------|------|------|
| $t_{d(on)}$ | Turn-on delay time | $V_{DD} = 400\text{ V}$, $I_D = 3\text{ A}$, $R_G = 4.7\text{ }\Omega$, $V_{GS} = 10\text{ V}$ (see Figure 14. Test circuit for resistive load switching times and Figure 19. Switching time waveform) | - | 12 | - | ns |
| t_r | Rise time | | - | 14 | - | ns |
| $t_{d(off)}$ | Turn-off delay time | | - | 32 | - | ns |
| t_f | Fall time | | - | 20 | - | ns |

Table 7. Source-drain diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------------|-------------------------------|--|------|------|------|---------------|
| I_{SD} | Source-drain current | | - | | 6 | A |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) | | - | | 24 | A |
| $V_{SD}^{(2)}$ | Forward on voltage | $I_{SD} = 6\text{ A}$, $V_{GS} = 0\text{ V}$ | - | | 1.5 | V |
| t_{rr} | Reverse recovery time | $I_{SD} = 6\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$, see Figure 16. Test circuit for inductive load switching and diode recovery times) | - | 300 | | ns |
| Q_{rr} | Reverse recovery charge | | - | 3 | | μC |
| I_{RRM} | Reverse recovery current | | - | 20 | | A |
| t_{rr} | Reverse recovery time | $I_{SD} = 6\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$, $T_j = 150\text{ }^\circ\text{C}$ (see Figure 16. Test circuit for inductive load switching and diode recovery times) | - | 415 | | ns |
| Q_{rr} | Reverse recovery charge | | - | 3.8 | | μC |
| I_{RRM} | Reverse recovery current | | - | 18 | | A |

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

Table 8. Gate-source Zener diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max | Unit |
|---------------|-------------------------------|---|----------|------|-----|------|
| $V_{(BR)GSO}$ | Gate-source breakdown voltage | $I_{GS} = \pm 1\text{ mA}$, $I_D = 0\text{ A}$ | ± 30 | - | - | V |

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.

2.1 Electrical characteristics (curves)

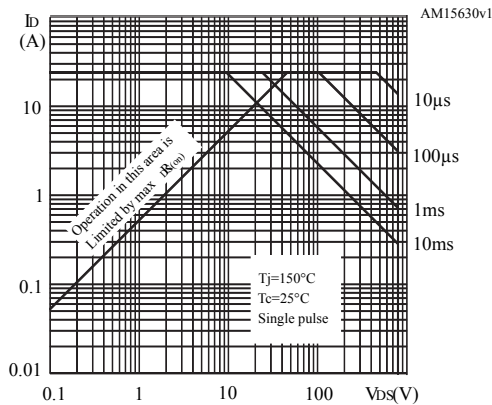
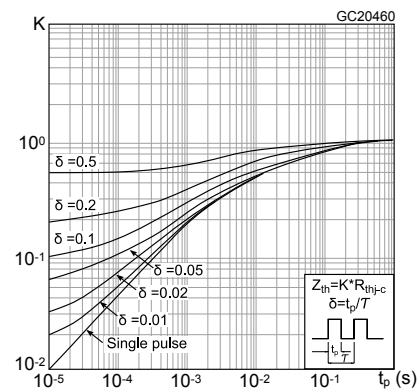
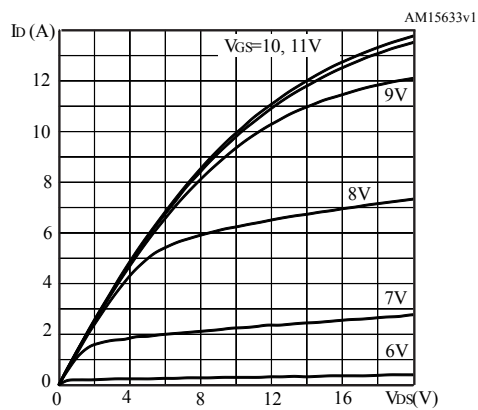
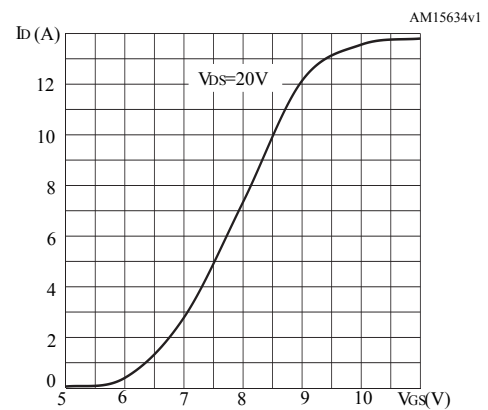
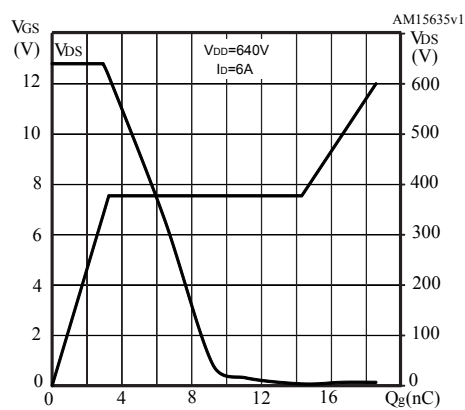
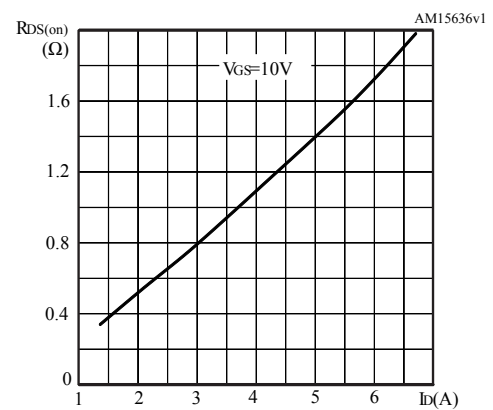
Figure 1. Safe operating area

Figure 2. Thermal impedance

Figure 3. Output characteristics

Figure 4. Transfer characteristics

Figure 5. Gate charge vs. gate-source voltage

Figure 6. Static drain-source on-resistance


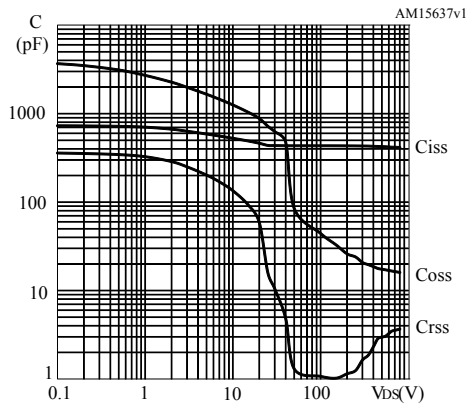
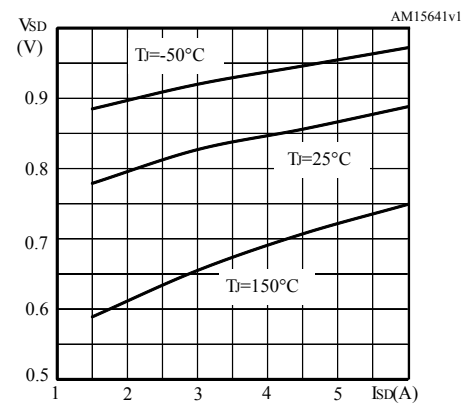
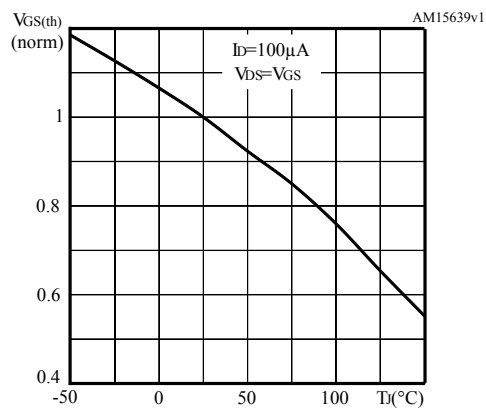
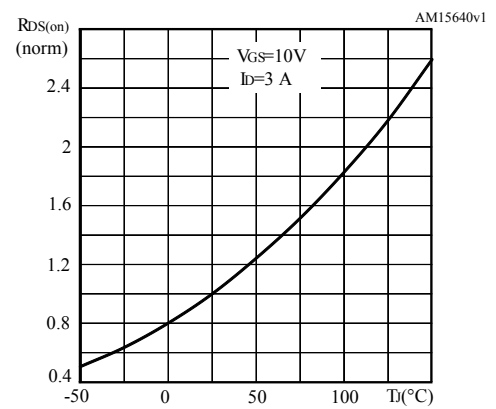
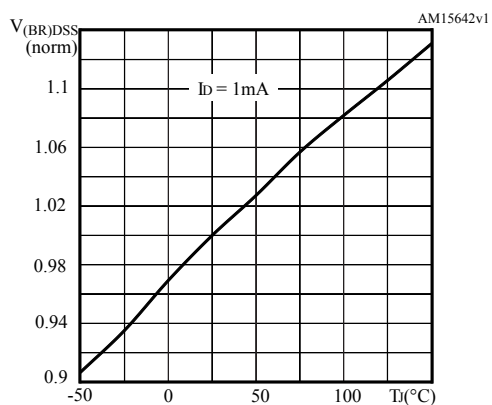
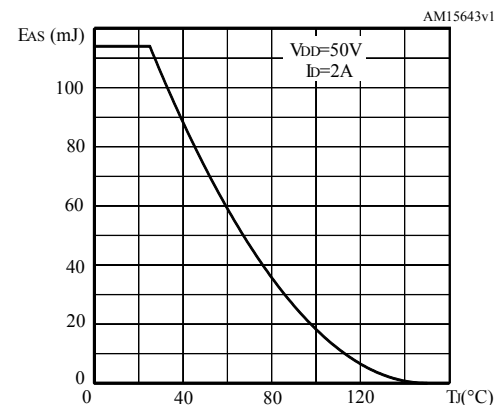
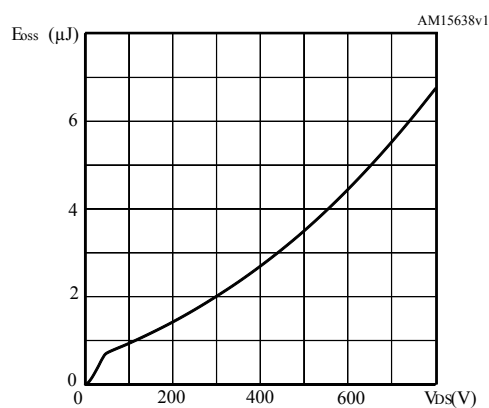
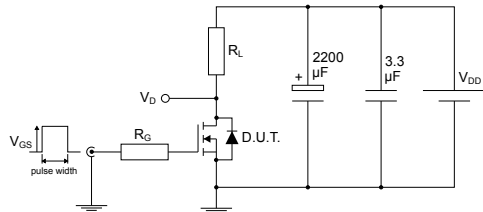
Figure 7. Capacitance variations

Figure 8. Source-drain diode forward characteristics

Figure 9. Normalized gate threshold voltage vs. temperature

Figure 10. Normalized on-resistance vs. temperature

Figure 11. Normalized $V_{(BR)DSS}$ vs. temperature

Figure 12. Maximum avalanche energy vs. starting T_J


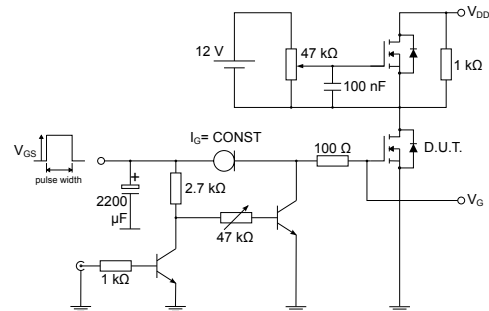
Figure 13. Output capacitance stored energy



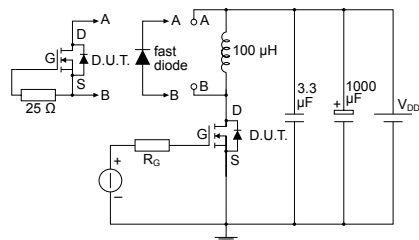
3 Test circuits

Figure 14. Test circuit for resistive load switching times


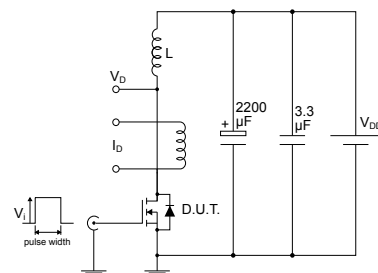
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Figure 15. Test circuit for gate charge behavior


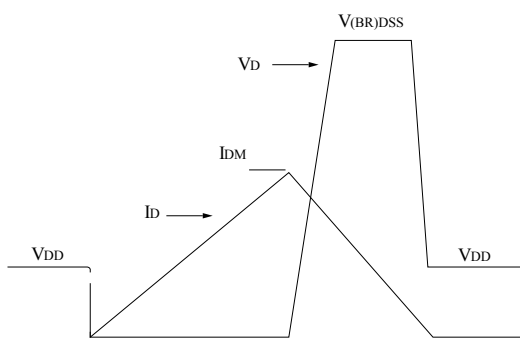
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Figure 16. Test circuit for inductive load switching and diode recovery times


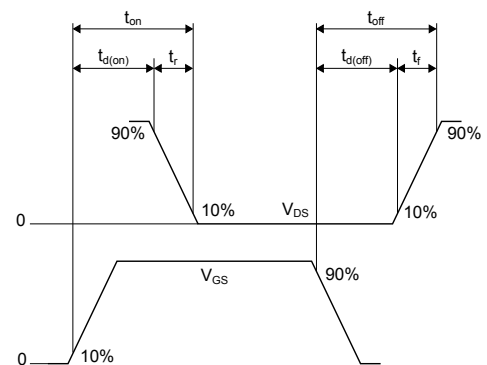
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Figure 17. Unclamped inductive load test circuit


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Figure 18. Unclamped inductive waveform


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Figure 19. Switching time waveform


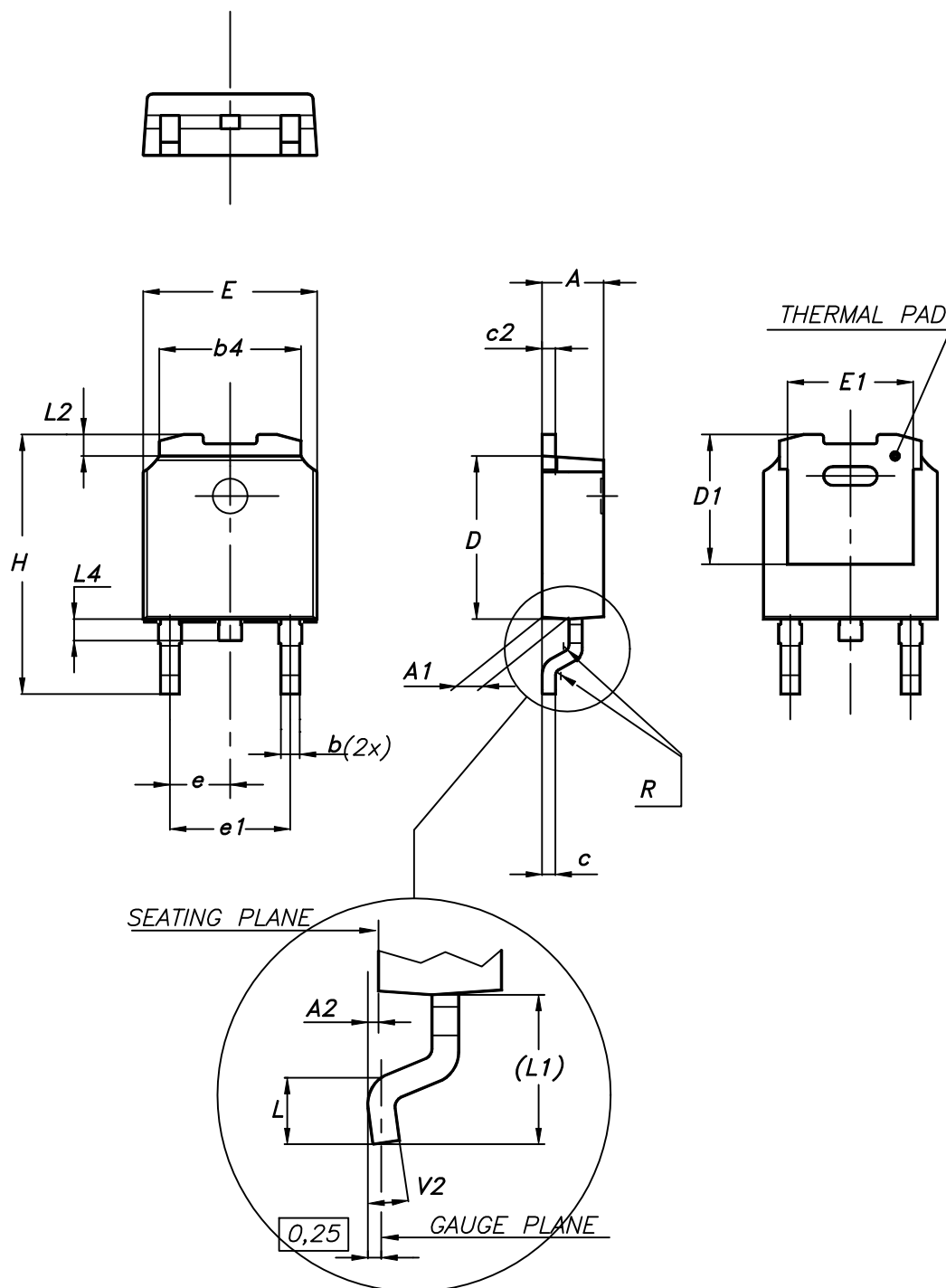
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4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 DPAK (TO-252) type A2 package information

Figure 20. DPAK (TO-252) type A2 package outline



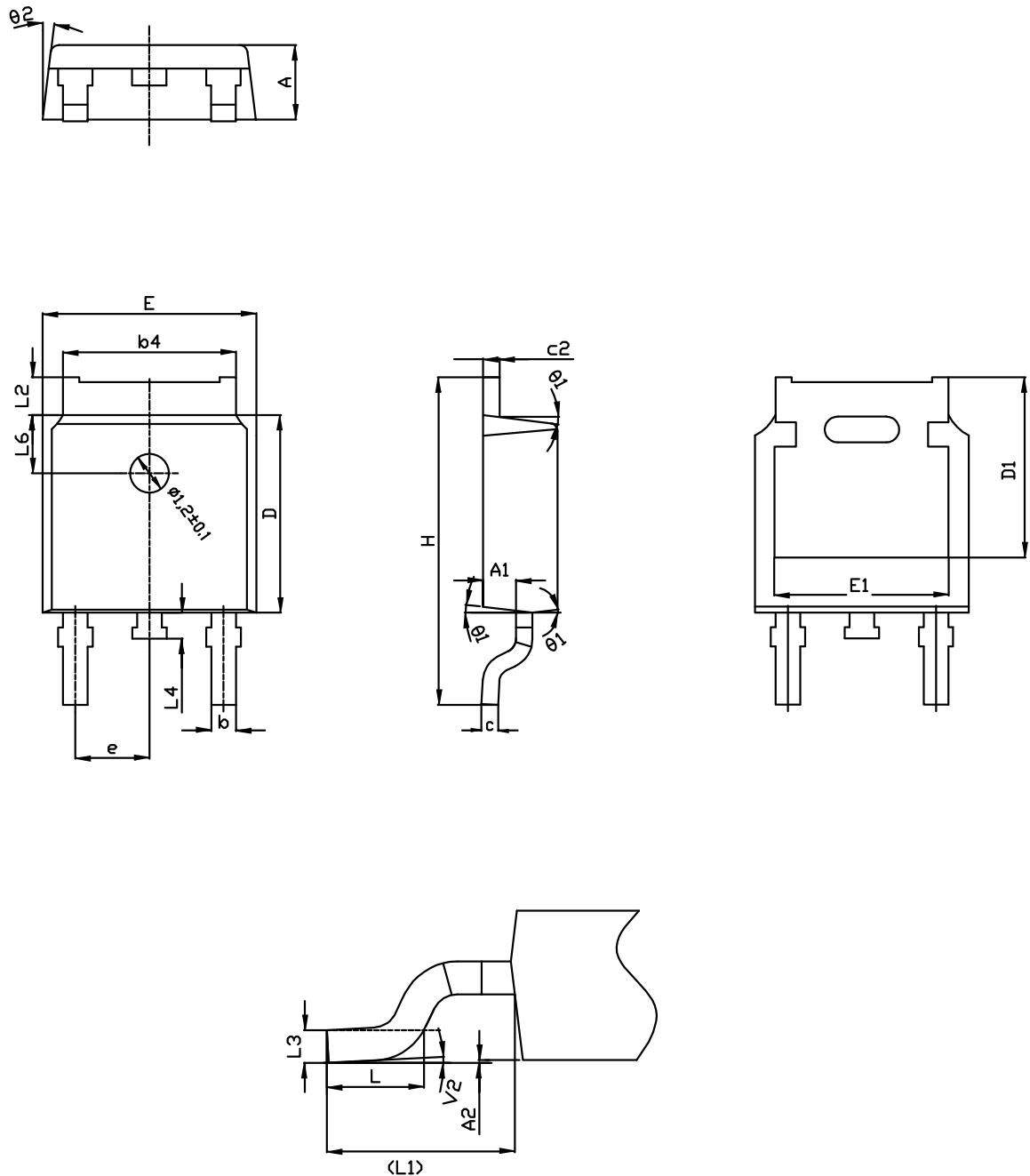
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Table 9. DPAK (TO-252) type A2 mechanical data

| Dim. | mm | | |
|------|-------|-------|-------|
| | Min. | Typ. | Max. |
| A | 2.20 | | 2.40 |
| A1 | 0.90 | | 1.10 |
| A2 | 0.03 | | 0.23 |
| b | 0.64 | | 0.90 |
| b4 | 5.20 | | 5.40 |
| c | 0.45 | | 0.60 |
| c2 | 0.48 | | 0.60 |
| D | 6.00 | | 6.20 |
| D1 | 4.95 | 5.10 | 5.25 |
| E | 6.40 | | 6.60 |
| E1 | 5.10 | 5.20 | 5.30 |
| e | 2.159 | 2.286 | 2.413 |
| e1 | 4.445 | 4.572 | 4.699 |
| H | 9.35 | | 10.10 |
| L | 1.00 | | 1.50 |
| L1 | 2.60 | 2.80 | 3.00 |
| L2 | 0.65 | 0.80 | 0.95 |
| L4 | 0.60 | | 1.00 |
| R | | 0.20 | |
| V2 | 0° | | 8° |

4.2 DPAK (TO-252) type C2 package information

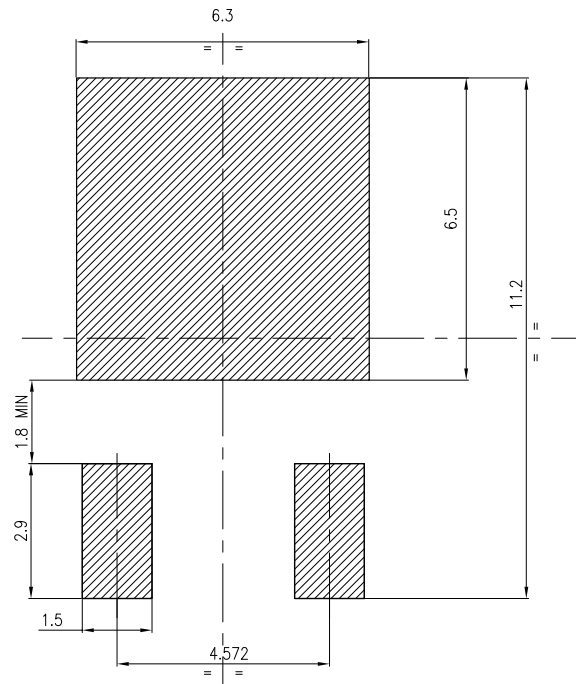
Figure 21. DPAK (TO-252) type C2 package outline



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Table 10. DPAK (TO-252) type C2 mechanical data

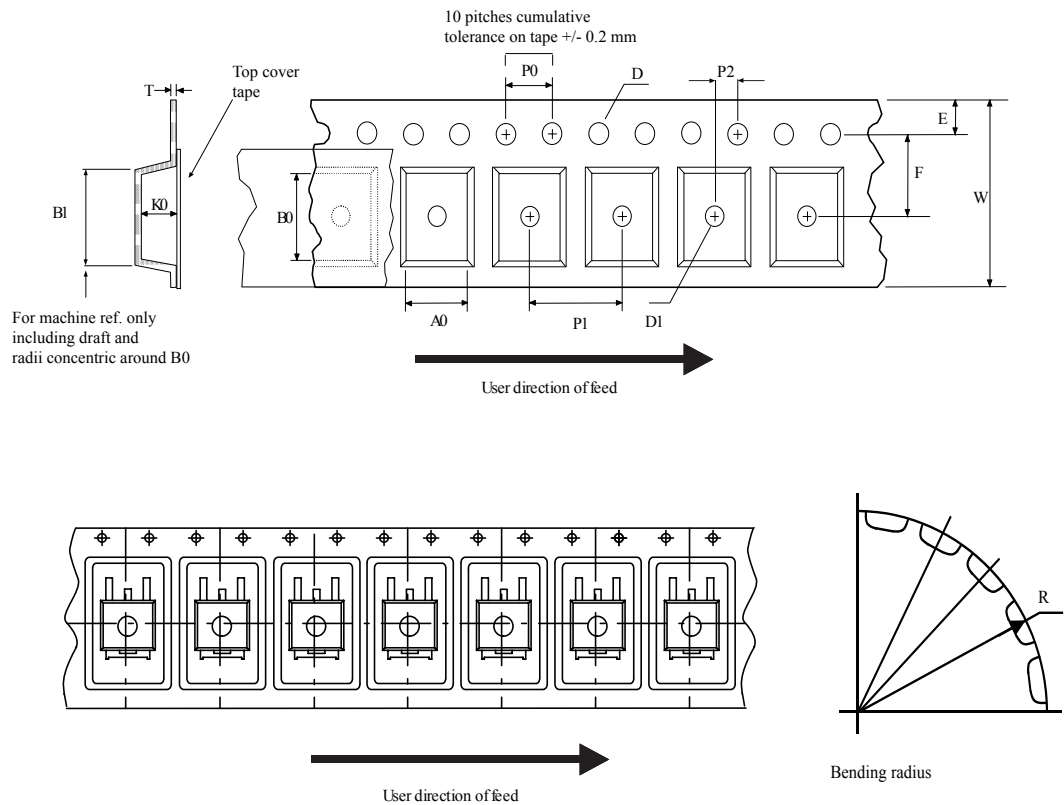
| Dim. | mm | | |
|------|----------|-------|-------|
| | Min. | Typ. | Max. |
| A | 2.20 | 2.30 | 2.38 |
| A1 | 0.90 | 1.01 | 1.10 |
| A2 | 0.00 | | 0.10 |
| b | 0.72 | | 0.85 |
| b4 | 5.13 | 5.33 | 5.46 |
| c | 0.47 | | 0.60 |
| c2 | 0.47 | | 0.60 |
| D | 6.00 | 6.10 | 6.20 |
| D1 | 5.10 | | 5.60 |
| E | 6.50 | 6.60 | 6.70 |
| E1 | 5.20 | | 5.50 |
| e | 2.186 | 2.286 | 2.386 |
| H | 9.80 | 10.10 | 10.40 |
| L | 1.40 | 1.50 | 1.70 |
| L1 | 2.90 REF | | |
| L2 | 0.90 | | 1.25 |
| L3 | 0.51 BSC | | |
| L4 | 0.60 | 0.80 | 1.00 |
| L6 | 1.80 BSC | | |
| θ1 | 5° | 7° | 9° |
| θ2 | 5° | 7° | 9° |
| V2 | 0° | | 8° |

Figure 22. DPAK (TO-252) recommended footprint (dimensions are in mm)


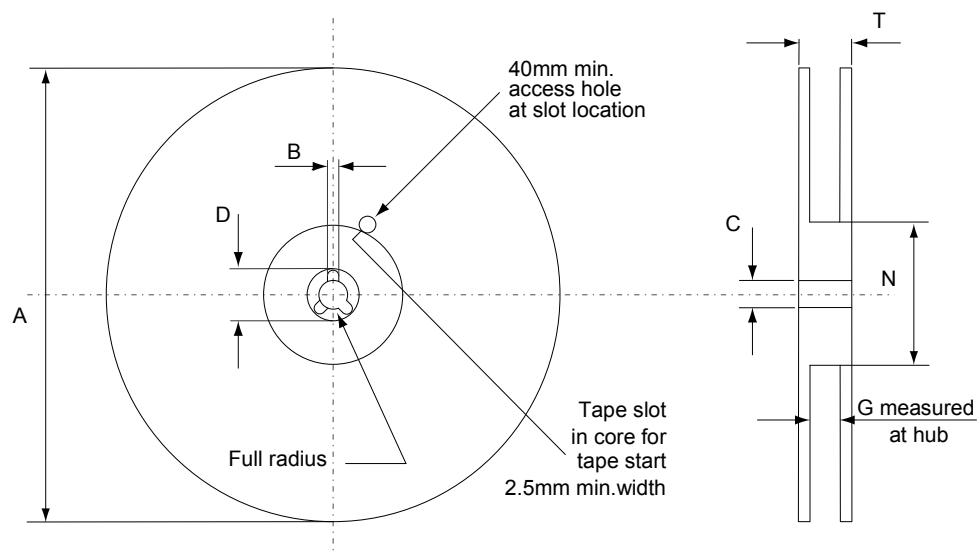
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4.3 DPAK (TO-252) packing information

Figure 23. DPAK (TO-252) tape outline



AM08852v1

Figure 24. DPAK (TO-252) reel outline


AM06038v1

Table 11. DPAK (TO-252) tape and reel mechanical data

| Tape | | | Reel | | |
|------|------|------|-----------|------|------|
| Dim. | mm | | Dim. | mm | |
| | Min. | Max. | | Min. | Max. |
| A0 | 6.8 | 7 | A | | 330 |
| B0 | 10.4 | 10.6 | B | 1.5 | |
| B1 | | 12.1 | C | 12.8 | 13.2 |
| D | 1.5 | 1.6 | D | 20.2 | |
| D1 | 1.5 | | G | 16.4 | 18.4 |
| E | 1.65 | 1.85 | N | 50 | |
| F | 7.4 | 7.6 | T | | 22.4 |
| K0 | 2.55 | 2.75 | | | |
| P0 | 3.9 | 4.1 | Base qty. | | 2500 |
| P1 | 7.9 | 8.1 | Bulk qty. | | 2500 |
| P2 | 1.9 | 2.1 | | | |
| R | 40 | | | | |
| T | 0.25 | 0.35 | | | |
| W | 15.7 | 16.3 | | | |

Revision history

Table 12. Document revision history

| Date | Revision | Changes |
|-------------|----------|--|
| 23-Mar-2013 | 1 | First release. Part number previously included in datasheet DM00062075 |
| 29-Mar-2013 | 2 | Added: MOSFET dv/dt ruggedness on <i>Table 2</i> |
| 20-Aug-2018 | 3 | Updated Section 4 Package information . Minor text changes. |

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